

Date Created : 2008/09/19
Date Issued On : 2008/10/27
PCN# : Q3083802

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:
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PCN Originator:
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Implementation of change:
Expected 1st Device Shipment Date: 2009/01/31

Earliest Year/Work Week of Changed Product: 0905

Change Type Description: Marking Method

Description of Change (From): Current top mark for SOIC 8L package assembly at FSC approved manufacturing location (Carsem) is using ink top mark.

Description of Change (To): To change the marking process for SOIC 8L package assembly at FSC approved manufacturing location (Carsem) to Laser top mark.

Reason for Change : The conversion of ink top mark to laser top mark for SO8 package assemble at Carsem to improve the quality of top marking process and to eliminate the use of ink which contain halogens on material used in the assembly process for ink marking. The fit/form/ functionality of the affected products remain un-changed. The affected products will be fully compliant to all published data sheet specifications.

Qual/REL Plan Numbers : Q20080419

N/A.

Qualification :

Reliability test is not required for marking method change.

Results/Discussion for Qual Plan Number - Q20080419

Test: (Mark Permanency) Conditions: Standard: JESD22-B107				
Lot	Device	Setpoint	Result	Failure Code
Q20080419AAMARK	FM75M8X		0/1	

Q20080419BAMARK	LMV358AM8X		0/1	
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Product Id Description : This Final PCN covers Fairchild Semiconductor SO8 packages assemble at Subcontractor Carsem. For a complete listing of products covered in this PCN release, please refer to the affected FSID listing.

Affected FSIDs :

FM75M8X	LMV358AM8X	
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